



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-07-20
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VNH7040AYTR-E	ARG(*VH74BAY	A	0959	2017-07-20
Amount	UoM	Unit type	ST ECOPACK Grade	
488.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	10.3-7.5-2.28	36	gull wing	
Comment	PSSO36L TRIPLE PAD			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.05	Die back side metal	98
Lead	2.38	Soft solder	4883

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ARG(*VH74BAY									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	8.407	mg	supplier	die	Silicon (Si)	7440-21-3		8.138	mg	968003	16676				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.079	mg	9397	162				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.033	mg	3925	68				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	476	9				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1427	25				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.048	mg	5710	98				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.004	mg	476	8				
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.089	mg	10586	182				
				Leadframe	Copper & its alloys	153.496	mg	supplier	alloy	Copper (Cu)	7440-50-8		147.447	mg	960592	302145
								supplier	alloy	Iron (Fe)	7439-89-6		3.468	mg	22593	7107
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.209	mg	1362	428				
supplier	alloy	Zinc (Zn)	7440-66-6						0.182	mg	1186	373				
supplier	metallization	Silver (Ag)	7440-22-4						2.190	mg	14267	4488				
supplier	metallization	Lead (Pb)	7439-92-1					7a-Lead in high met	2.383	mg	975041	4883				
Soft solder	Solder	2.444	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.037	mg	15139	76				
				supplier	solder	Tin (Sn)	7440-31-5		0.024	mg	9820	49				
				supplier	solder	Gold (Au)	7440-57-5		3.376	mg	859023	6918				
Bonding wires	Other inorganic materials	3.930	mg	supplier	wire	Copper (Cu)	7440-50-8		0.554	mg	140967	1135				
				supplier	wire	silica vitreous	60676-86-0		276.984	mg	878001	567590				
Encapsulation	Other Organic Materials	315.471	mg	supplier	mold compound	Biphenyl epoxy resin	85954-11-6		18.928	mg	59999	38787				
				supplier	mold compound	Phenol Resin	205830-20-2		12.619	mg	40001	25859				
				supplier	mold compound	epoxy resin	25068-38-6		6.309	mg	19999	12928				
				supplier	mold compound	carbon black	1333-86-4		0.631	mg	2000	1293				
Connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	8713				